

## General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

## Features

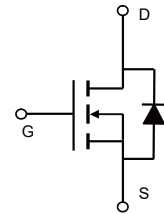
- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

## Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)



TO-252



Schematic

| Parameter                                              | Symbol          | Value      | Unit          |
|--------------------------------------------------------|-----------------|------------|---------------|
| Drain-Source Voltage ( $V_{GS}=0V$ )                   | $V_{DS}$        | 650        | V             |
| Gate-Source Voltage ( $V_{DS}=0V$ ), AC ( $f>1$ Hz)    | $V_{GS}$        | $\pm 30$   | V             |
| Gate-Source Voltage ( $V_{DS}=0V$ ), DC                | $V_{GS}$        | $\pm 20$   | V             |
| Continuous Drain Current at $T_c=25^\circ C$           | $I_{D(DC)}$     | 17         | A             |
| Continuous Drain Current at $T_c=100^\circ C$          | $I_{D(DC)}$     | 11.9       | A             |
| Pulsed drain current (Note 1)                          | $I_{DM(pluse)}$ | 51         | A             |
| Maximum Power Dissipation( $T_c=25^\circ C$ )          | $P_D$           | 172        | W             |
| Derate above $25^\circ C$                              |                 | 1.15       | W/ $^\circ C$ |
| Single pulse avalanche current (Note 2)                | $I_{AS}$        | 3.5        | A             |
| Reverse diode $dv/dt$ , $V_{DS} \leq 480V, I_{SD}<I_D$ | $dv/dt$         | 15         | V/ns          |
| Drain Source voltage slope, $V_{DS} \leq 480V$         | $dv/dt$         | 50         | V/ns          |
| Operating Junction and Storage Temperature Range       | $T_J, T_{STG}$  | -55...+175 | $^\circ C$    |

**Table 2. Thermal Characteristic**

| Parameter                                         | Symbol     | Value | Unit                        |
|---------------------------------------------------|------------|-------|-----------------------------|
| Thermal Resistance, Junction-to-Case (Maximum)    | $R_{thJC}$ | 0.87  | $^{\circ}\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Ambient (Maximum) | $R_{thJA}$ | 62    | $^{\circ}\text{C}/\text{W}$ |

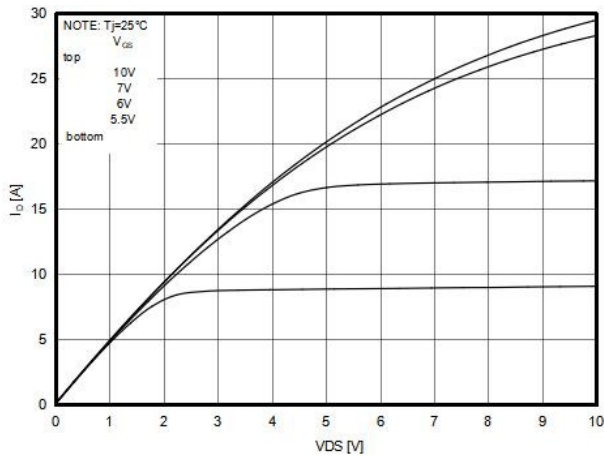
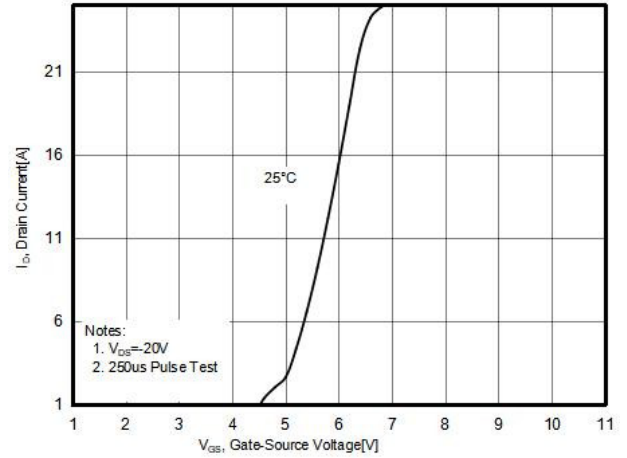
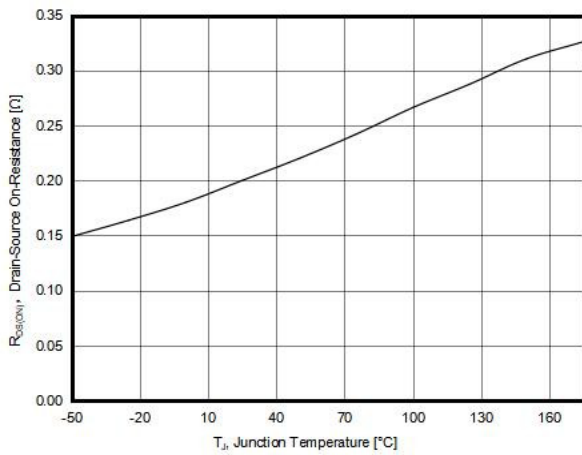
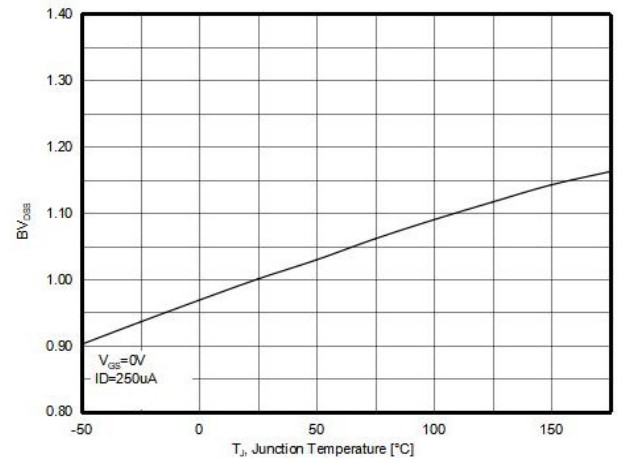
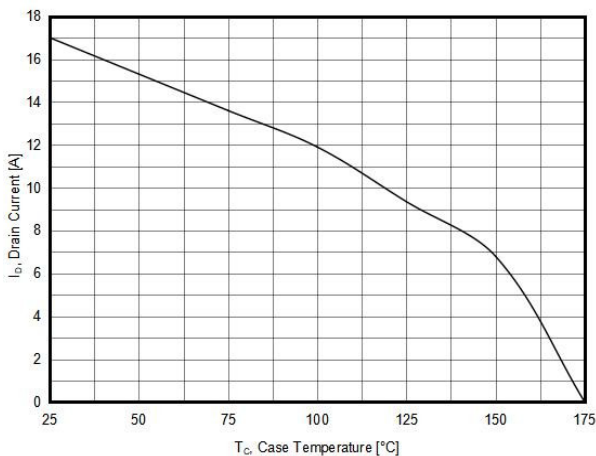
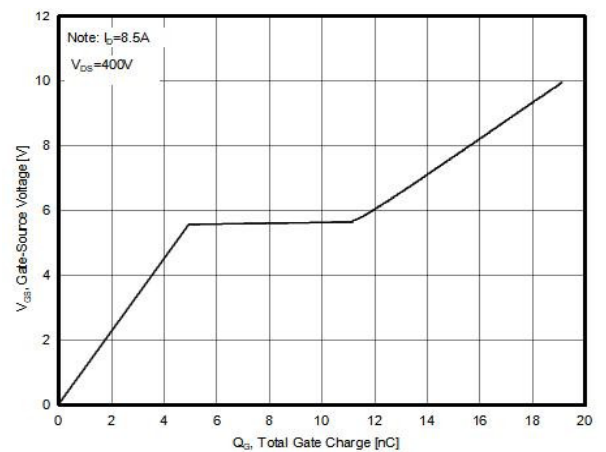
**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

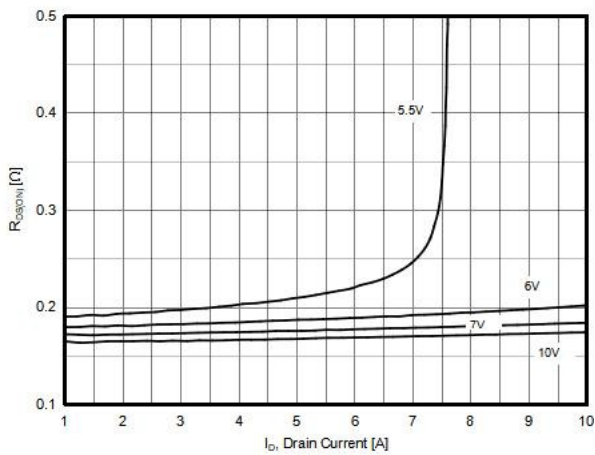
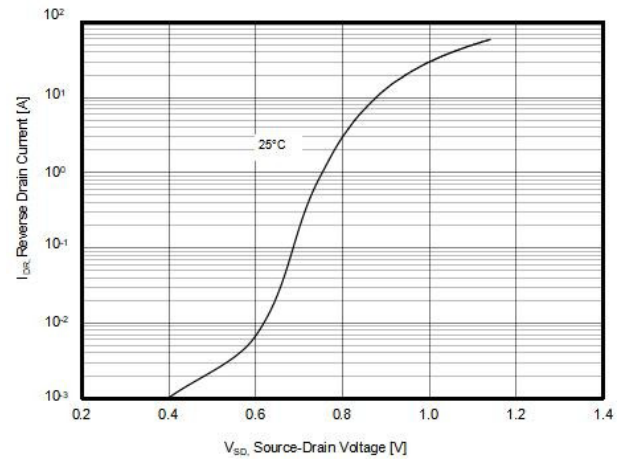
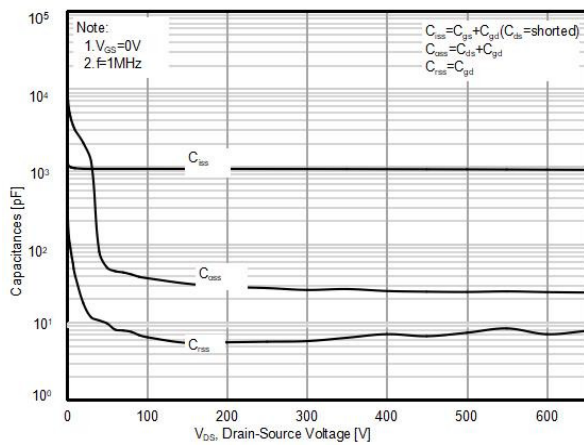
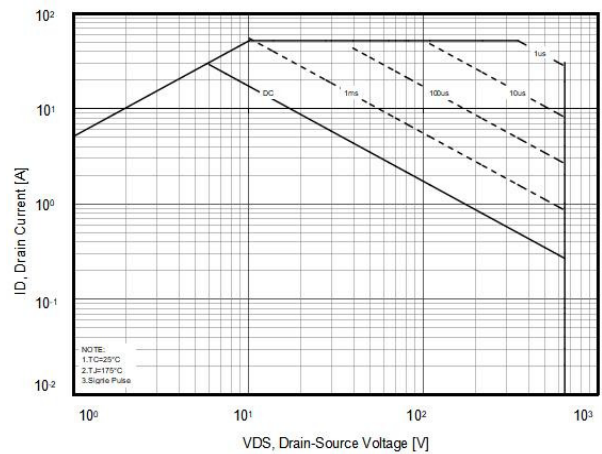
| Parameter                                | Symbol              | Condition                                                                              | Min | Typ   | Max  | Unit |
|------------------------------------------|---------------------|----------------------------------------------------------------------------------------|-----|-------|------|------|
| On/off states                            |                     |                                                                                        |     |       |      |      |
| Drain-Source Breakdown Voltage           | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250uA                                              | 650 |       |      | V    |
| Zero Gate Voltage Drain Current(Tc=25℃)  | I <sub>DSS</sub>    | V <sub>DS</sub> =650V,V <sub>GS</sub> =0V                                              |     |       | 1    | μA   |
| Zero Gate Voltage Drain Current(Tc=125℃) | I <sub>DSS</sub>    | V <sub>DS</sub> =650V,V <sub>GS</sub> =0V                                              |     |       | 100  | μA   |
| Gate-Body Leakage Current                | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V                                              |     |       | ±200 | nA   |
| Gate Threshold Voltage                   | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA                                | 3   | 3.5   | 4    | V    |
| Drain-Source On-State Resistance         | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A                                             |     | 190   | 230  | mΩ   |
| Dynamic Characteristics                  |                     |                                                                                        |     |       |      |      |
| Gate Resistance                          | R <sub>g</sub>      | F=1MHZ, D-S short                                                                      |     | 18    |      | Ω    |
| Input Capacitance                        | C <sub>iss</sub>    | V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,<br>F=1MHz                                    |     | 930   | 1100 | pF   |
| Output Capacitance                       | C <sub>oss</sub>    |                                                                                        |     | 50    |      | pF   |
| Reverse Transfer Capacitance             | C <sub>rss</sub>    |                                                                                        |     | 2     |      | pF   |
| Total Gate Charge                        | Q <sub>g</sub>      | V <sub>DS</sub> =400V,I <sub>b</sub> =8.5A,<br>V <sub>GS</sub> =10V                    |     | 19    |      | nC   |
| Gate-Source Charge                       | Q <sub>gs</sub>     |                                                                                        |     | 5.0   |      | nC   |
| Gate-Drain Charge                        | Q <sub>gd</sub>     |                                                                                        |     | 6.2   |      | nC   |
| Gate plateau voltage                     | V <sub>gp</sub>     |                                                                                        |     | 5.6   |      | V    |
| Switching times                          |                     |                                                                                        |     |       |      |      |
| Turn-on Delay Time                       | t <sub>d(on)</sub>  | V <sub>DD</sub> =400V,I <sub>b</sub> =8.5A,<br>R <sub>G</sub> =4Ω,V <sub>GS</sub> =10V |     | 10    |      | nS   |
| Turn-on Rise Time                        | t <sub>r</sub>      |                                                                                        |     | 8     |      | nS   |
| Turn-Off Delay Time                      | t <sub>d(off)</sub> |                                                                                        |     | 56    |      | nS   |
| Turn-Off Fall Time                       | t <sub>f</sub>      |                                                                                        |     | 10    |      | nS   |
| Source- Drain Diode Characteristics      |                     |                                                                                        |     |       |      |      |
| Source-drain current(Body Diode)         | I <sub>SD</sub>     | T <sub>C</sub> =25℃                                                                    |     |       | 17   | A    |
| Pulsed-Source-drain current(Body Diode)  | I <sub>SDM</sub>    |                                                                                        |     |       | 51   | A    |
| Forward on voltage                       | V <sub>SD</sub>     | T <sub>j</sub> =25℃,I <sub>SD</sub> =17A,V <sub>GS</sub> =0V                           |     | 0.9   | 1.2  | V    |
| Reverse Recovery Time                    | t <sub>rr</sub>     | T <sub>j</sub> =25℃,I <sub>F</sub> =8.5A,<br>di/dt=100A/μs                             |     | 245   |      | nS   |
| Reverse Recovery Charge                  | Q <sub>rr</sub>     |                                                                                        |     | 2.205 |      | uC   |
| Peak reverse recovery current            | I <sub>rrm</sub>    |                                                                                        |     | 18    |      | A    |

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2.  $T_j=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

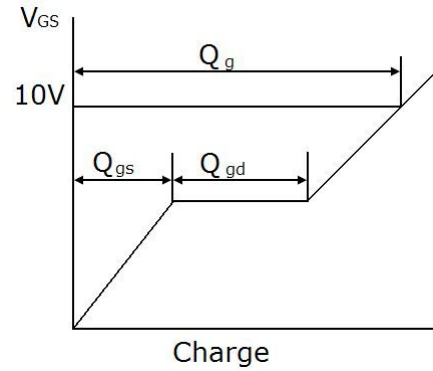
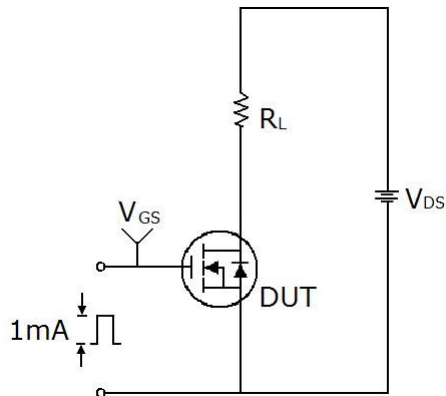
## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

**Figure1. Output characteristics**

**Figure2. Transfer characteristics**

**Figure3.  $R_{DS(ON)}$  vs Junction Temperature**

**Figure4.  $BV_{DSS}$  vs Junction Temperature**

**Figure5. Maximum  $I_D$  vs Junction Temperature**

**Figure6. Gate charge waveforms**


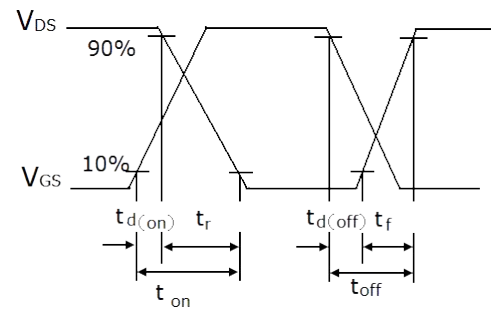
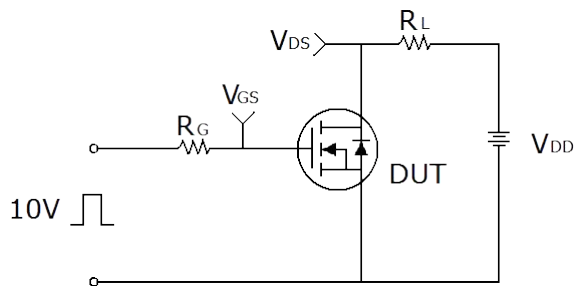
**Figure7. Static drain-source on resistance**

**Figure8. Source-Drain Diode Forward Voltage**

**Figure9. Capacitance**

**Figure10. Safe operating area**


## Test circuit

### 1) Gate charge test circuit & Waveform



### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms

